Product / Package Information

Package	TSSOP_4.4
Body Size (mm)	4.4
Lead Count	24
Terminal Finish	100 Sn
MS Number	MS010618C

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	4.25E-02	86.91	869100	48.61	486106
Thermosets	Epoxy & Phenol Resin	Proprietary	6.25E-03	12.78	127800	7.15	71481
Other inorganic materials	Carbon black	1333-86-4	1.52E-04	0.31	3100	0.17	1734
Subtotal			4.89 E-02	100.00	1000000	55.93	559321

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.83 E-02	96.20	962000	32.39	323900
Copper & its alloys	Nickel	7440-02-0	8.83 E-04	3.00	30000	1.01	10101
Copper & its alloys	Silicon	7440-21-3	1.91 E-04	0.65	6500	0.22	2189
Copper & its alloys	Magnesium	7439-95-4	4.41 E-05	0.15	1500	0.05	505
Subtotal			2.94 E-02	100.00	1000000	33.67	336694

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.97 E-04	100.0	1000000	0.34	3401

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.93 E-03	100.0	1000000	2.21	22111

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	7.36 E-04	100.0	1000000	0.84	8418

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	4.49 E-03	100.0	1000000	5.13	51320

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.27 E-03	77.71	777100	1.46	14560
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	5.09 E-05	3.11	31100	0.06	583
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	5.09 E-05	3.11	31100	0.06	583
Other organic materials	Butyrolactone, gamma-	96-48-0	5.09 E-05	3.11	31100	0.06	583
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	5.09 E-05	3.11	31100	0.06	583
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	5.09 E-05	3.11	31100	0.06	583
Other organic materials	Organosilane	TS ref# 10001	5.09 E-05	3.11	31100	0.06	583
Other inorganic materials	Copper(II) oxide	1317-38-0	5.09 E-05	3.11	31100	0.06	583
Other organic materials	Epoxy resin modifier	TS ref# 10038	8.52 E-06	0.52	5200	0.01	97
Subtotal			1.64 E-03	100.0	1000000	1.87	18736

	Weight (g)	Percentage (%)	PPM
Package Totals	**8.74 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to
any inaccuracy of such information.

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